

# East of USPB, USPT, WPID, JPO

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	107735	(resist or photoresist or mask or photomask).clm.	US-PGPUB; USPAT	OR	ON	2005/10/24 19:05
L2	683307	(etch\$ or patern\$ or remov\$).clm.	US-PGPUB; USPAT	OR	ON	2005/10/24 19:06
L3	267478	(bond\$ or laminat\$).clm.	US-PGPUB; USPAT	OR	ON	2005/10/24 19:06
L4	502591	(wafer or semiconduct\$ or chip or substrate).clm.	US-PGPUB; USPAT	OR	ON	2005/10/24 19:08
L5	12538	1 with 2 with 4	US-PGPUB; USPAT	OR	ON	2005/10/24 18:53
L6	48770	3 with 4	US-PGPUB; USPAT	OR	ON	2005/10/24 18:53
L7	1085	5 and 6	US-PGPUB; USPAT	OR	ON	2005/10/24 18:53
L8	1727138	(active or device or circuit or component).clm.	US-PGPUB; USPAT	OR	ON	2005/10/24 19:07
L9	17991	3 with 4 with 8	US-PGPUB; USPAT	OR	ON	2005/10/24 18:54
L10	461	5 and 9	US-PGPUB; USPAT	OR	ON	2005/10/24 18:54
L11	636	bevel\$ with 4	US-PGPUB; USPAT	OR	ON	2005/10/24 18:55
L12	1	10 and 11	US-PGPUB; USPAT	OR	ON	2005/10/24 18:55
L13	1	10 and bevel\$.clm.	US-PGPUB; USPAT	OR	ON	2005/10/24 18:55
L14	27	10 and soi	US-PGPUB; USPAT	OR	ON	2005/10/24 18:56
L15	434	10 not 14	US-PGPUB; USPAT	OR	ON	2005/10/24 18:56
L16	27	10 not 15	US-PGPUB; USPAT	OR	ON	2005/10/24 18:56
L17	27	16 not 12	US-PGPUB; USPAT	OR	ON	2005/10/24 19:00
L18	12038	intel.as.	US-PGPUB; USPAT	OR	ON	2005/10/24 19:00
L19	16	1 and 2 and 3 and 4 and 18	US-PGPUB; USPAT	OR	ON	2005/10/24 19:00
L20	0	19 and bevel\$.clm.	US-PGPUB; USPAT	OR	ON	2005/10/24 19:01
L21	11	19 and 8	US-PGPUB; USPAT	OR	ON	2005/10/24 19:02
L22	473	(morrow-p\$ or list-r\$ or chan-m\$).in.	US-PGPUB; USPAT	OR	ON	2005/10/24 19:03

L23	2	1 and 2 and 3 and 4 and 22	US-PGPUB; USPAT	OR	ON	2005/10/24 19:04
L24	10	1 and 2 and 3 and bevel\$.clm. and 8	US-PGPUB; USPAT	OR	ON	2005/10/24 19:05
L25	0	24 and 18	US-PGPUB; USPAT	OR	ON	2005/10/24 19:05
L26	1	24 and 22	US-PGPUB; USPAT	OR	ON	2005/10/24 19:05
L27	501246	resist or photoresist or mask or photomask	US-PGPUB; USPAT	OR	ON	2005/10/24 19:22
L28	2536837	etch\$ or patern\$ or remov\$	US-PGPUB; USPAT	OR	ON	2005/10/24 19:23
L29	943762	bond\$ or laminat\$	US-PGPUB; USPAT	OR	ON	2005/10/24 19:23
L30	3899085	active or device or circuit or component	US-PGPUB; USPAT	OR	ON	2005/10/24 19:24
L31	109495	bevel\$	US-PGPUB; USPAT	OR	ON	2005/10/24 19:24
L32	9634	27 same 28 same 29 same 30	US-PGPUB; USPAT	OR	ON	2005/10/24 19:08
L33	1209942	wafer or semiconduct\$ or chip or substrate	US-PGPUB; USPAT	OR	ON	2005/10/24 19:23
L34	6625	32 same 33	US-PGPUB; USPAT	OR	ON	2005/10/24 19:09
L35	71065	27 with 28 with 33	US-PGPUB; USPAT	OR	ON	2005/10/24 19:10
L36	68242	29 with 30 with 33	US-PGPUB; USPAT	OR	ON	2005/10/24 19:11
L37	1339	34 same 35 same 36	US-PGPUB; USPAT	OR	ON	2005/10/24 19:11
L38	1	31 same 37	US-PGPUB; USPAT	OR	ON	2005/10/24 19:12
L39	1339	35 same 36	US-PGPUB; USPAT	OR	ON	2005/10/24 19:13
L40	12	39 and bevel\$	US-PGPUB; USPAT	OR	ON	2005/10/24 19:13
L41	1	40 and (soi or "si\$ on insulat\$")	US-PGPUB; USPAT	OR	ON	2005/10/24 19:17
L42	11	40 not 41	US-PGPUB; USPAT	OR	ON	2005/10/24 19:17
L43	156	35 and 36 and bevel\$	US-PGPUB; USPAT	OR	ON	2005/10/24 19:17
L44	26	43 and (soi or "si\$ on insulat\$")	US-PGPUB; USPAT	OR	ON	2005/10/24 19:18
L45	9869	35 and 36	US-PGPUB; USPAT	OR	ON	2005/10/24 19:18

L46	9843	45 not 44	US-PGPUB; USPAT	OR	ON	2005/10/24 19:18
L47	26	45 not 46	US-PGPUB; USPAT	OR	ON	2005/10/24 19:19
L48	350861	resist or photoresist or mask or photomask	JPO; DERWENT	OR	ON	2005/10/24 19:22
L49	1711071	etch\$ or patern\$ or remov\$	JPO; DERWENT	OR	ON	2005/10/24 19:23
L50	2064081	wafer or semiconduct\$ or chip or substrate	JPO; DERWENT	OR	ON	2005/10/24 19:23
L51	994786	bond\$ or laminat\$	JPO; DERWENT	OR	ON	2005/10/24 19:23
L52	33963	bevel\$	JPO; DERWENT	OR	ON	2005/10/24 19:24
L53	8046801	active or device or circuit or component	JPO; DERWENT	OR	ON	2005/10/24 19:24
L54	9	48 and 49 and 50 and 51 and 52	JPO; DERWENT	OR	ON	2005/10/24 19:25
L55	5	53 and 54	JPO; DERWENT	OR	ON	2005/10/24 19:25
L56	4	54 not 55	JPO; DERWENT	OR	ON	2005/10/24 19:26